## Rad hard MOSFET nomenclature

<table>
<thead>
<tr>
<th>Transistor type</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>H</td>
<td>Radiation hardened HEXFET</td>
</tr>
<tr>
<td>HL</td>
<td>Rad hard logic level MOSFET</td>
</tr>
<tr>
<td>HS</td>
<td>Rad hard synchronous rectifier</td>
</tr>
<tr>
<td>HSL</td>
<td>Rad hard synchronous rectifier (low inductance)</td>
</tr>
</tbody>
</table>

### Package designator

All packages have metal lids unless otherwise noted:

- Blank: TO-204AA, AE (TO-3)
- C: Chip/die (no package)
- W: Wafer (no package)
- E: LCC-18
- G: MO-036AB (14 lead ceramic DIP)
- I: TO-259A
- M: TO-254AA
- MB: TO-254AA tabless, new ohmic
- MK: TO-254AA tabless, low ohmic, surface mount lead formed - at surface plane
- ML: TO-254AA tabless, low ohmic, surface mount lead formed - below surface plane
- MS: TO-254AA low ohmic
- N: SMD-1
- NA: SMD-2
- NJ: SMD-0.5
- NJC: SMD-0.5, ceramic lid
- NK: SMD-0.5e, enhanced, ceramic lid, NM
- NMC: SMD-0.2, ceramic lid
- NME: SMD-0.2e, enhanced, ceramic lid
- NPC: SMD-0.1, ceramic lid
- NS: SupIR-SMD™
- PB: Power Block, isolated
- Q: LCC-28 (quad die)
- UB: LCC-4-pads, shielded to 4th pin
- UBC: LCC-4-pads, ceramic lid, shielded
- UBCN: LCC-3-pads, ceramic lid, isolated
- UBN: LCC-3-pads, isolated
- UC: LCC-6-pads
- V: TO-250AA
- Y: TO-257AA
- YA: TO-257AA tabless
- YB: TO-257AA tabless, low ohmic
- YJ: TO-257AA tabless, surface mount lead formed
- YK: TO-257AA tabless, low ohmic, surface mount lead formed
- YS: TO-257AA low ohmic
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### Technology

- Blank: R4 (HEXFET)
- 5: R5
- 5S: R5, S-line
- 6: R6
- 6S: R6, S-line
- 7: R7
- 7S: R7, S-line
- 8: R8
- 9A: R9

### Channel

- Blank: N-channel
- 6: Mixed N and P channel
- 9: P-channel

### Lead option

- A: Lead form down on TO-25x
- B: Lead form up on TO-25x
- C: Lead trimmed (TO-25x packages only)
- D: On DBC carrier, applies only to SMD-1 and SMD-2

### Screening Level

- Blank: no screening, COTS
- CDV: 100% die visual inspection
- CDH: H level, MIL-PRF-19500, Appendix G
- CDK: K level, MIL-PRF-19500, Appendix G

### Process variation

- Blank: Single event effect tolerant (applicable only to R4 & R5)

### Pinout

- Blank: (applies only to TO-257AA packages)
- Pin1: Gate
- Pin2: Drain
- Pin3: Source

### Package variation

- Blank: glass eyelet (all TO-257AA packages)
- C: ceramic eyelet (all TO-257AA packages)

### Voltage adder

- Full spec rating (does not apply to 60 V devices)
- 30 V, e.g. 1x3 is 130 V
- 50 V, e.g. 2x4 is 250 V or, 0x4 is 60 V

### Die size

- 1
- 2
- 3
- 4
- 5
- 6
- 7
- 8
- 9

### Voltage (BV_{DSS})

- 0: 60 V
- 1: 100 V (or 130 V or 150 V with voltage adder)
- 2: 200 V (or 250 V with voltage adder)
- 3: 400 V
- 4: 500 V (or 550 V with voltage adder)
- C: 600 V
- Y: 20 V
- Z: 30 V

### Total dose hardness

- Blank: 100 krad(Si) P-channel (R4 only)
- 3: 300 krad(Si)
- 4: 500 krad(Si)
- 7: 100 krad(Si)
- 8: 1000 krad(Si)
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